



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

HP Compaq 6005 Pro Ultra Slim Desktop Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2 (1 in computer, 1 in power supply)
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		4
Components, parts and materials containing		

radioactive substances		
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	
Description #3 Torx screwdriver	T-15, T8

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. To remove the access panel, loosen the thumbscrew on the rear of the computer (1), slide the access panel toward the front of the computer, and then lift it off (2). (see Figure 1).
2. To remove the front bezel, lift up the three tabs on the side of the bezel (1), then rotate the bezel off the chassis (2) (see Figure 2).
3. Remove or cut all expansion cards, cables, and any other devices from the system board.
4. To remove the system board:
 - a. Remove the hard drive (see Figures 3-6 to remove the hard drive carrier and the drive from the carrier).
 - b. Remove the hard drive cage by removing the two Torx T15 screws that secure the cage to the chassis (1), lifting the tab (2) on the hard drive cage, sliding the cage toward the rear of the unit, and then pulling the cage up and out of the chassis (3) (see Figure 7).
 - c. Remove the front I/O panel by removing the screw from the right side of the cage that secures the I/O panel cage to the front of the chassis (1), pressing the tab on right side of the cage (2), and then swinging the right side of the cage away from the chassis to remove it (3) (see Figure 8).
 - d. Remove the heatsink from the system board by loosening the four captive screws that secure the heatsink to the system board, and then lifting the heatsink from the system board (see Figure 9).
 - e. Remove the three screws (1) that secure the system board to the chassis.
 - f. Slide system board toward the front of the unit (2) until the rear connectors are clear of their slots in the chassis, lift the rear of the system board until it clears the chassis, and then remove the system board from the chassis (see Figure 10).
5. To remove the battery, pull back on the clip (1) that holds the battery in place, then remove the battery (2) (see Figure 11).
6. To disassemble the external power supply:
 - a. Remove the covers (see Figures 12, 13, 14)
 - b. Remove the aluminum shielding (see Figure 15, 16, 17)
 - c. Remove the sheet metal shields (see Figures 18, 19, 20)
 - d. Remove the capacitor as shown in Figure 21)
 - e. Remove the external cable that requires selective treatment (see Figure 22)
 - f. Remove components containing ceramic fibers (see Figure 23, 24)
 - g. The remaining component (printed wiring board) requires selective treatment (see Figure 25)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the access panel.



FIGURE 2: Removing the front bezel

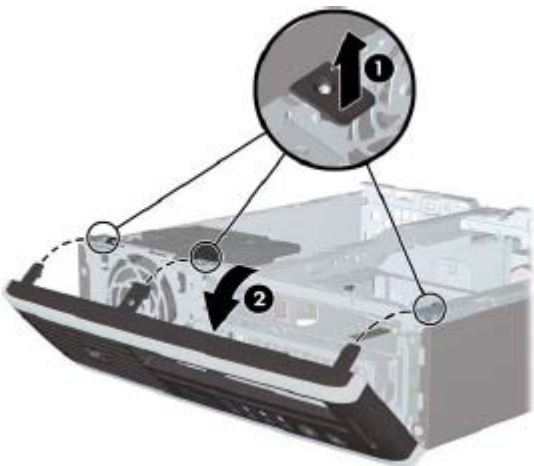


FIGURE 3: Unlocking the hard drive carrier

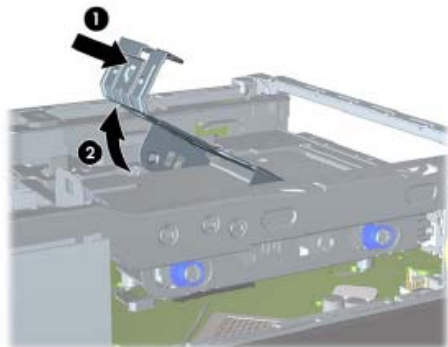


FIGURE 4: Removing the hard drive carrier

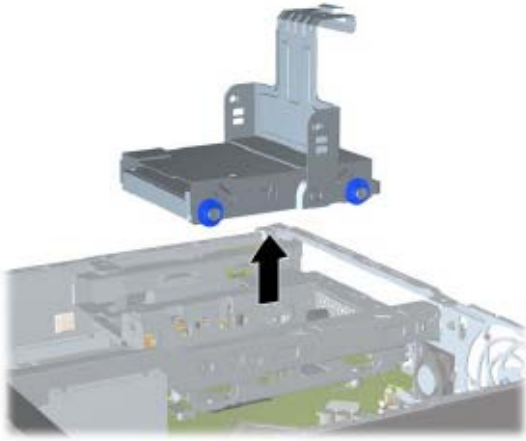


FIGURE 5: Removing the guide screws



FIGURE 6: Removing the hard drive from the carrier

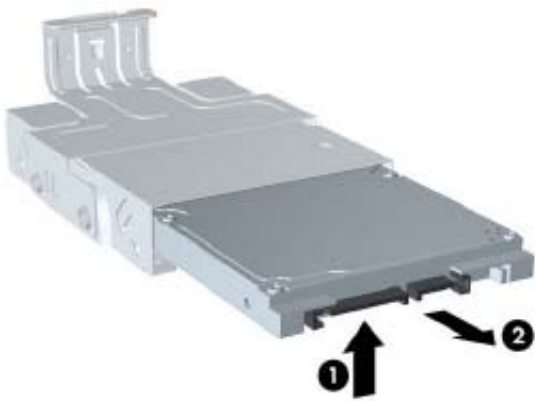


FIGURE 7: Removing the drive cage

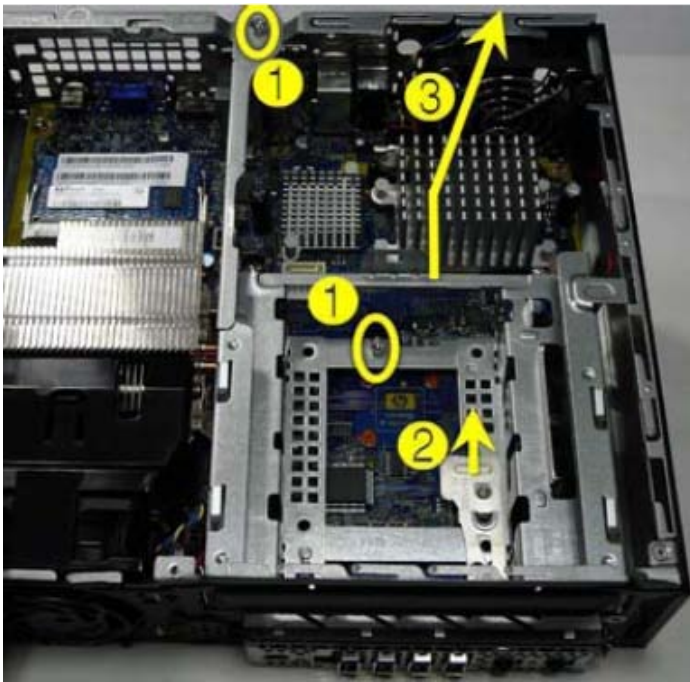


FIGURE 8: Removing the front I/O cage



FIGURE 9: Heat sink screw locations



FIGURE 10: System board screw locations



FIGURE 11: Removing the battery



FIGURE 12: Removing the power supply covers



FIGURE 13: Removing the power supply cover



FIGURE 14: Removing the power supply bottom cover



FIGURE 15: Removing the tape



FIGURE 16: Removing the bottom aluminum shielding



FIGURE 17: Disconnecting the top aluminum shielding



FIGURE 18: Removing the sheet metal shielding: Tear foil



FIGURE 19: Removing the sheet metal shielding: Remove two screws

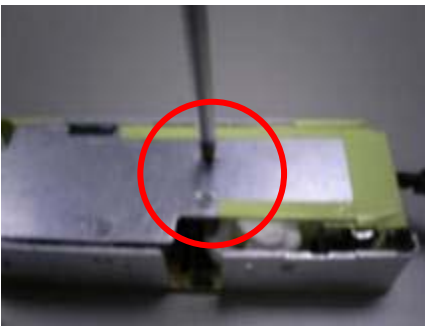


FIGURE 20: Removing the sheet metal shielding: Lift shielding off

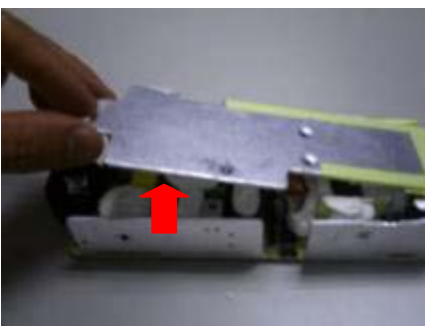


FIGURE 21: Remove the capacitor as shown below

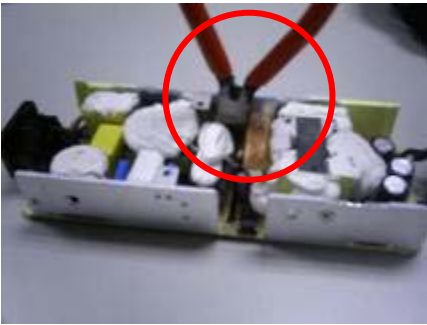


FIGURE 22: Cut the external cable



FIGURE 23: Removing the white thermal paste

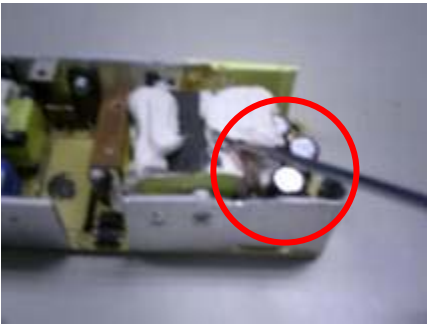


FIGURE 24: Removing the components with ceramic fibers

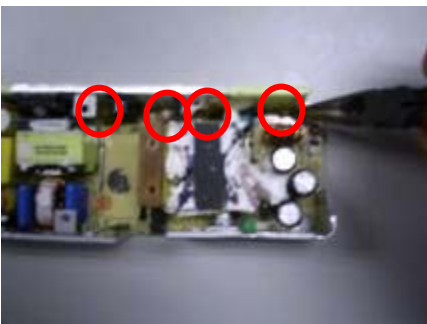


FIGURE 25: Printed wiring board

